

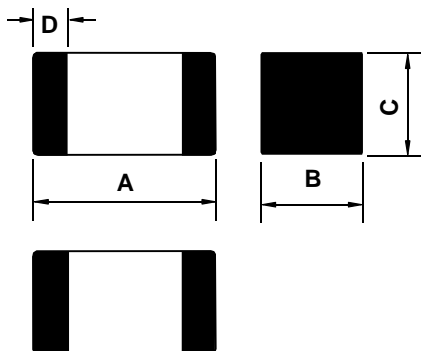
FEATURES

Closed Magnetic circuit structure allows high density mounting while preventing crosstalk.
 Extremely high reliability due to entirely monolithic construction.
 Low DC resistance structure of electrode to prevent wasteful electric power consumption.
 High Current rating up to 6A.
 The products contain no lead and also support lead-free soldering.

APPLICATIONS

Personal computers, Communication equipment, Digital telephone, Electronic games machines, CRTs, Hard disk drives, cellular phones, PDAs, Printers High current DC lines and other computer peripheral products.

DIMENSIONS

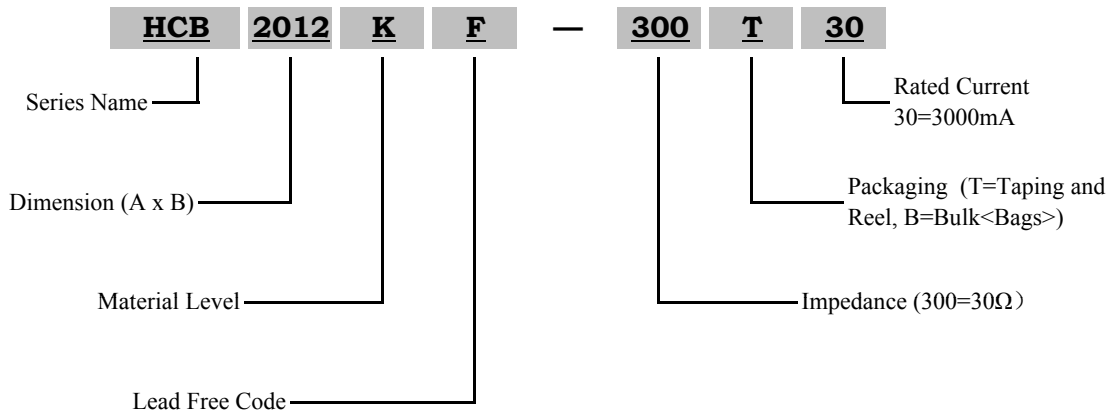


Chip Size:2012

A	B	C	D
2.0±0.20	1.25±0.20	0.85±0.20	0.50±0.30

All dimensions in units:mm

PART NUMBERING

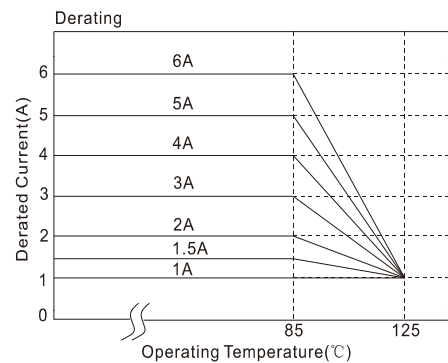


SPECIFICATION

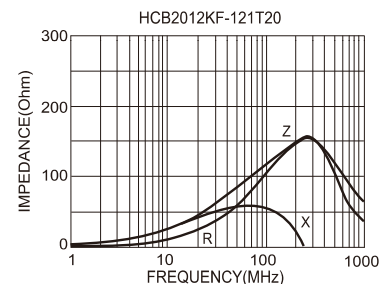
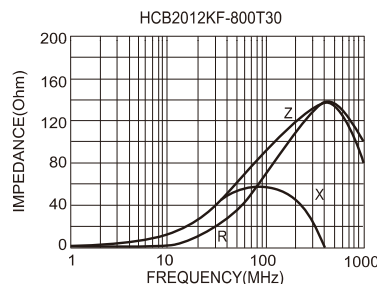
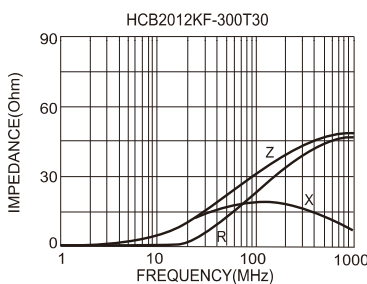
Part Number	Impedance (Ohm)	Test Frequency (MHz)	Rated Current (mA)max.	DCR (Ohm)max.
HCB2012KF-300T30	30±25%	100	3000	0.04
HCB2012KF-800T30	80±25%	100	3000	0.04
HCB2012KF-121T20	120±25%	100	2000	0.10
HCB2012KF-151T20	150±25%	100	2000	0.10
HCB2012KF-221T20	220±25%	100	2000	0.10
HCB2012KF-301T10	300±25%	100	1000	0.20
HCB2012KF-471T10	470±25%	100	1000	0.20
HCB2012KF-601T10	600±25%	100	1000	0.20

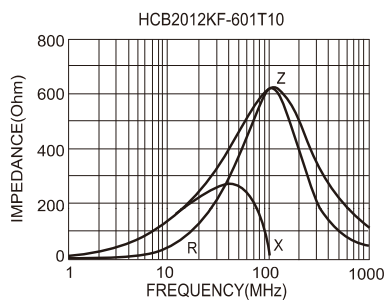
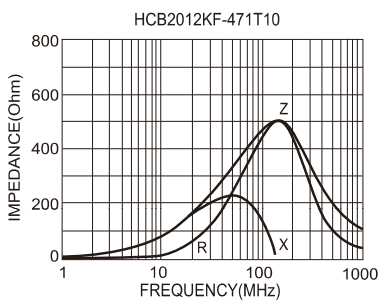
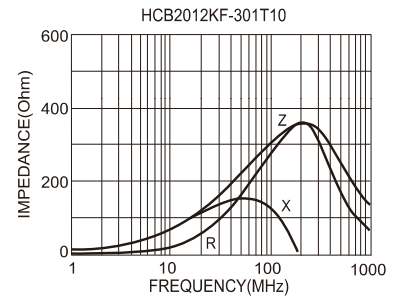
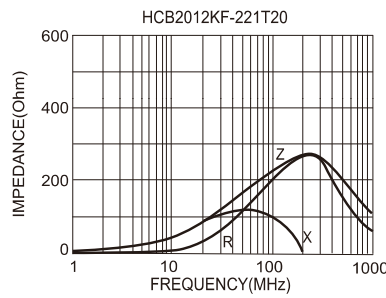
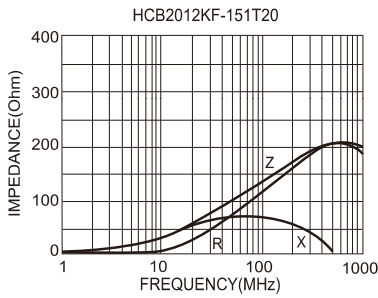
Derating Curve

For the ferrite chip bead which withstanding current over 1.5A, as the operating temperature over 85°C, the derating current information is necessary to consider with. For the detail derating of current, please refer to the Derated Current vs. Operating Temperature curve.



Typical Impedance V.s. Frequency Curve



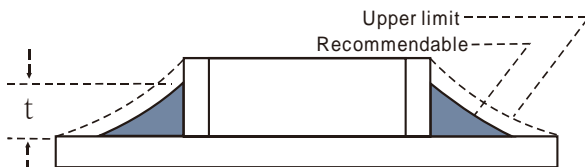
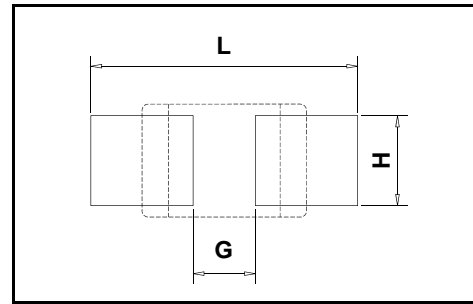


SOLDERING AND MOUNTING

RECOMMENDED PC BOARD PATTERN

Land Patterns For Reflow Soldering

Size	L(mm)	G(mm)	H(mm)
2012	3.00	1.00	1.00

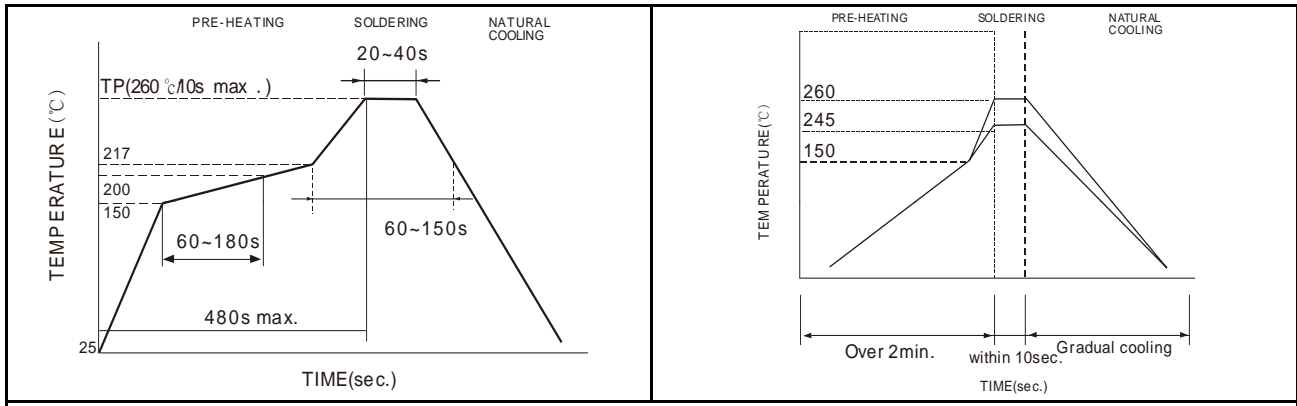


Accordingly increasing the solder volume, the mechanical stress to product is also increased. Exceeding solder volume may cause the failure of mechanical or electrical performance. Solder shall be used not to be exceed as shown in left side.

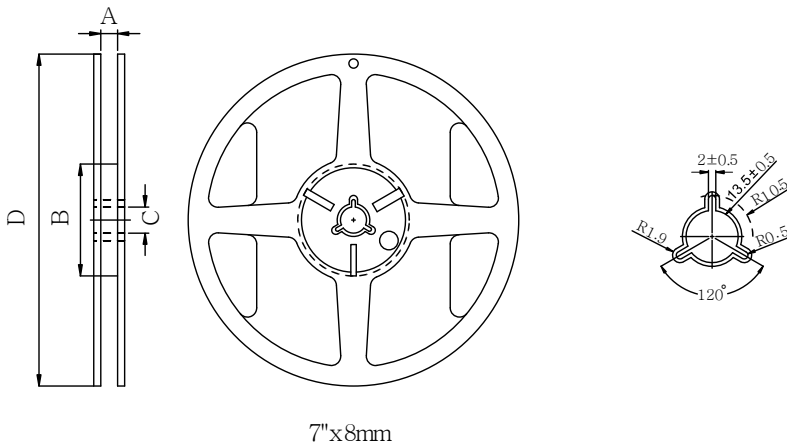
RECOMMENDED SOLDERING CONDITIONS

Reflow Soldering

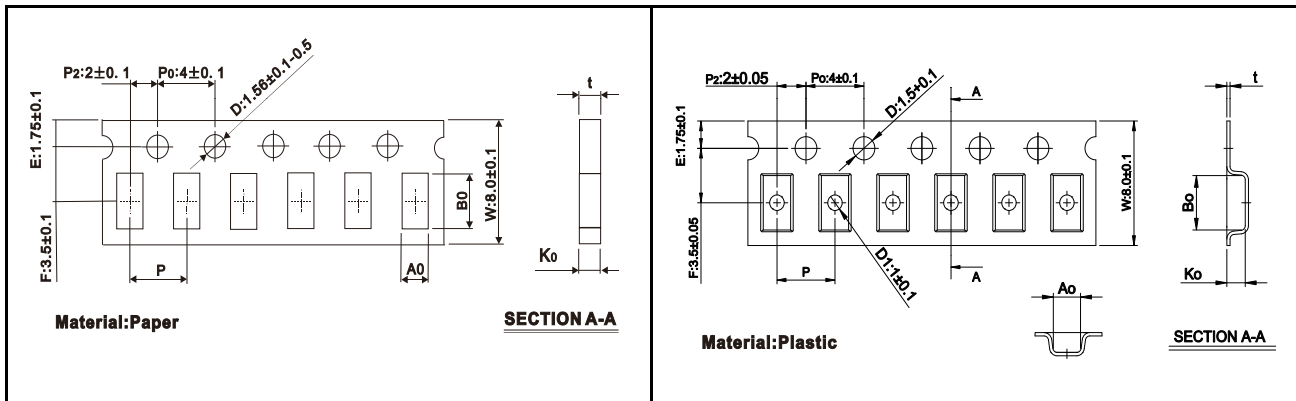
Wave Soldering



PACKAGING INFORMATION



Type	A(mm)	B(mm)	C(mm)	D(mm)
7" x 8mm	9±0.5	60±2	13.5±0.5	178±2



Series	Bo (mm)	Ao (mm)	Ko (mm)	P (mm)	t (mm)
201209	2.30±0.05	1.50±0.05	0.95±0.05	4.0±0.10	0.95±0.05

Series	Bo (mm)	Ao (mm)	Ko (mm)	P (mm)	t (mm)	D1 (mm)
201209	2.25±0.10	1.42±0.10	1.04±0.10	4.0±0.10	0.22±0.05	1.0±0.10

PACKAGING QUANTITY

Size	Chip/Reel	Inner Box	Middle Box	Carton
201209	4000	20000	100000	200000

Application Notice
●Storage Conditions

To maintain the solderability of terminal electrodes:

1. Temperature and humidity conditions: -10~40°C and 30~70% RH.
2. Recommended products should be used within 6 months from the time of delivery.
3. The packaging material should be kept where on chlorine or sulfur exists in the air.

●Transportation

1. Products should be handled with care to avoid damage or contamination from perspiration and skin oils.
2. The use of tweezers or vacuum pick up is strongly recommended for individual components.
3. Bulk handling should ensure that abrasion and mechanical shock are minimized.

All the data listed in this catalogue are for reference only, COILS-TECH reserves the right to alter. Specifications are subject to change without notice.